

Dear Customer,

Please find attached our INFINEON Technologies PCN:

Dresden Fab Transfer for D2Pak Package

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **10-September-2016**.
- Infineon aligns with the widely-recognized JEDEC STANDARD “**JESD46**“, which stipulates:
“**Lack of acknowledgment of the PCN within 30 days constitutes acceptance of the change.**”

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG
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Chairman of the Supervisory Board: Wolfgang Mayrhofer
Management Board: Dr. Reinhard Ploss (CEO), Dominik Asam, Dr. Helmut Gassel, Jochen Hanebeck
Registered Office: Neubiberg Commercial Register
Amtsgericht München HRB 126492

Dresden Fab Transfer for D2Pak Package

► Products affected:

See attached for affected parts.

► Detailed Change Information:

Subject: Add Dresden 300MM as qualified Fab for Gen 10.7 D2Pak products

Reason: Expansion of wafer production and wafer test capacity.

Description: Dresden Fab Transfer for D2Pak Package

Site	Old	New
Fab	Vanguard International Semiconductor or	Infineon Technologies AG, Dresden, Germany or
Fab	Infineon Technologies Newport Limited	Vanguard International Semiconductor or
Fab		Infineon Technologies Newport Limited

► Product Identification: Wafer fab origins will not be distinguished through the external part marking or shipping labels, however, based on the assembly lot code and marked on the device. IFX internal systems will be able to trace the site of the wafer lots used to produce the final product.

► Impact of Change: No changes to form, fit, or function. The package outline remains the same. Datasheet specifications will not be changed. The package bill of material and the location for assembly and final test will not change.

► Attachments: 960-DISTI42-C4002348_AffectedParts.xlsx

► Time Schedule:

- Final qualification report: available
- First samples available: on request
- Intended start of delivery: 22-September-2016

If you have any questions, please do not hesitate to contact your local Sales office.

PCN N° 960-DISTI42-C4002348-Private
Dresden Fab Transfer for D2Pak Package



Removed IRF1018ESLPBF,IRF1018ESTRLPBF,IRFS3806TRLPBF

Sales Name	SP number	OPN	Package
IRFS3004TRLPBF	SP001557246	IRFS3004TRLPBF	D2PAK
IRFS3006PBF	SP001568064	IRFS3006PBF	D2PAK
IRFS3006TRLPBF	SP001567578	IRFS3006TRLPBF	D2PAK
IRFS3107PBF	SP001573388	IRFS3107PBF	D2PAK
IRFS3107TRLPBF	SP001576238	IRFS3107TRLPBF	D2PAK
IRFS3206PBF	SP001557264	IRFS3206PBF	D2PAK
IRFS3206TRRPBF	SP001573508	IRFS3206TRRPBF	D2PAK
IRFS3207ZPBF	SP001567946	IRFS3207ZPBF	D2PAK
IRFS3207ZTRRPBF	SP001565050	IRFS3207ZTRRPBF	D2PAK
IRFS3306PBF	SP001578320	IRFS3306PBF	D2PAK
IRFS3306TRLPBF	SP001568056	IRFS3306TRLPBF	D2PAK
IRFS3307ZPBF	SP001576230	IRFS3307ZPBF	D2PAK
IRFS3307ZTRLPBF	SP001565042	IRFS3307ZTRLPBF	D2PAK
IRFS4010PBF	SP001578304	IRFS4010PBF	D2PAK
IRFS4010TRLPBF	SP001550124	IRFS4010TRLPBF	D2PAK
IRFS4310ZPBF	SP001557322	IRFS4310ZPBF	D2PAK
IRFS4310ZTRLPBF	SP001557376	IRFS4310ZTRLPBF	D2PAK
IRFS4410ZPBF	SP001576190	IRFS4410ZPBF	D2PAK
IRFS4410ZTRLPBF	SP001567800	IRFS4410ZTRLPBF	D2PAK
IRFSL3004PBF	SP001578466	IRFSL3004PBF	TO262
IRFSL3006PBF	SP001573396	IRFSL3006PBF	TO262
IRFSL3107PBF	SP001557588	IRFSL3107PBF	TO262
IRFSL3206PBF	SP001578476	IRFSL3206PBF	TO262
IRFSL3207ZPBF	SP001552364	IRFSL3207ZPBF	TO262
IRFSL3306PBF	SP001568072	IRFSL3306PBF	TO262
IRFSL3607PBF	SP001565218	IRFSL3607PBF	TO262
IRFSL4010PBF	SP001567760	IRFSL4010PBF	TO262
IRFSL4310ZPBF	SP001557618	IRFSL4310ZPBF	TO262
IRFSL4410ZPBF	SP001557638	IRFSL4410ZPBF	TO262

